

ABSTRACT

Disclosed in the present invention is a method for cleaning an electroplating device. When the electroplating device is cleaned, a partition is used for replacing an ionic membrane framework to separate a cathode chamber and an anode chamber, such that the cathode chamber and the anode chamber are independently cleaned. After an electroplating chamber is cleaned, an exhaust pipe is used for emptying the cleaning solution remaining in the anode chamber and in the liquid inlet channel arranged in a sidewall of the anode chamber, such that no cleaning solution remains after the electroplating chamber is cleaned, thereby eliminating the effect of the residual cleaning solution on the ionic concentration ratio of an electroplating solution in electroplating solution preparation procedures.